



PMP10801 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP10801	Any	Printed Circuit Board	
C1	1	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, C0G/NP0, 0402	0402
C2	1	22uF	GRM31CR61C226ME15L	MuRata	CAP, CERM, 22 uF, 16 V, +/- 20%, X5R, 1206	1206
C3	1	2.2uF	C1005X5R1C225K050BC	TDK	CAP, CERM, 2.2uF, 16V, +/-10%, X5R, 0402	0402
C4	1	10uF	C1608X5R1A106M	TDK	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603
C5, C6	2	47uF	C3216X5R0J476M	TDK	CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 1206	1206
C7	1	4700pF	GRM155R71H472KA01D	MuRata	CAP, CERM, 4700 pF, 50 V, +/- 10%, X7R, 0402	0402
D1	1	40V	B240A-13-F	Diodes Inc.	Diode, Schottky, 40 V, 2 A, SMA	SMA
D2	1	6.2V	BZT52C6V2T-7	Diodes Inc.	Diode, Zener, 6.2 V, 300 mW, SOD-523	SOD-523
L1	1	2.2uH	LPD5030-222MRB	Coilcraft	Coupled inductor, 2.2 uH, 3.07 A, 0.067 ohm, +/- 20%, SMD	4.8x4.8x2.9mm
L2	1	220 ohm	MPZ1608S221A	TDK	Ferrite Bead, 220 ohm @ 100 MHz, 2.2 A, 0603	0603
R1	1	1.00k	CRCW04021K00FKED	Vishay-Dale	RES, 1.00k ohm, 1%, 0.063W, 0402	0402
R2	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R3	1	100	CRCW0402100RJNED	Vishay-Dale	RES, 100, 5%, 0.063 W, 0402	0402
R4	1	140	CRCW0402140RFKED	Vishay-Dale	RES, 140, 1%, 0.063 W, 0402	0402
R5	1	46.4k	CRCW040246K4FKED	Vishay-Dale	RES, 46.4 k, 1%, 0.063 W, 0402	0402
TP1, TP3	2	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
TP2, TP4	2	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
U1	1		TPS54335DRCR	Texas Instruments	4.5V to 28V Input, 3A Output, Synchronous SWIFT Step-Down DC-DC Converter, DRC0010J	DRC0010J

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